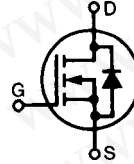


HiPerFET™ Power MOSFETs

IXFH/IXFT 30N50
IXFH/IXFT 32N50

N-Channel Enhancement Mode
High dv/dt, Low t_{rr} , HDMOS™ Family

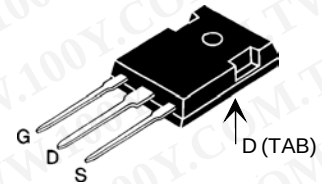


V_{DSS}	I_{D25}	$R_{DS(on)}$
500 V	30 A	0.16 Ω
500 V	32 A	0.15 Ω

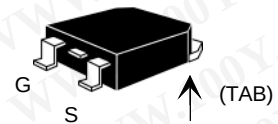
$t_{rr} \leq 250$ ns

Symbol	Test Conditions	Maximum Ratings
V_{DSS}	$T_J = 25^\circ\text{C}$ to 150°C	500 V
V_{DGR}	$T_J = 25^\circ\text{C}$ to 150°C ; $R_{GS} = 1\text{ M}\Omega$	500 V
V_{GS}	Continuous	± 20 V
V_{GSM}	Transient	± 30 V
I_{D25}	$T_C = 25^\circ\text{C}$	30N50 30 A 32N50 32 A
I_{DM}	$T_C = 25^\circ\text{C}$ pulse width limited by T_{JM}	30N50 120 A 32N50 128 A
I_{AR}	$T_C = 25^\circ\text{C}$	30N50 30 A 32N50 32 A
E_{AS}	$T_C = 25^\circ\text{C}$	1.5 J
E_{AR}	$I_D = 25^\circ\text{C}$	45 mJ
dv/dt	$I_S \leq I_{DM}$, di/dt $\leq 100\text{ A}/\mu\text{s}$, $V_{DD} \leq V_{DSS}$, $T_J \leq 150^\circ\text{C}$, $R_G = 2\text{ }\Omega$	5 V/ns
P_D	$T_C = 25^\circ\text{C}$	360 W
T_J		-55 ... +150 $^\circ\text{C}$
T_{JM}		150 $^\circ\text{C}$
T_{stg}		-55 ... +150 $^\circ\text{C}$
T_L	1.6 mm (0.062 in.) from case for 10 s	300 $^\circ\text{C}$
M_d	Mounting torque	1.13/10 Nm/lb.in.
Weight		6 g

TO-247 AD (IXFH)



TO-268 (D3) Case Style



G = Gate, D = Drain,
S = Source, TAB = Drain

Features

- International standard packages
- Low $R_{DS(on)}$ HDMOS™ process
- Rugged polysilicon gate cell structure
- Unclamped Inductive Switching (UIS) rated
- Low package inductance
- easy to drive and to protect
- Fast intrinsic Diode

Applications

- DC-DC converters
- Battery chargers
- Switched-mode and resonant-mode power supplies
- DC choppers
- AC motor control
- Temperature and lighting controls

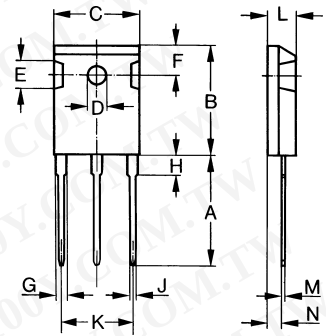
Advantages

- Easy to mount with 1 screw (TO-247) (isolated mounting screw hole)
- Space savings
- High power density

Symbol	Test Conditions	Characteristic Values ($T_J = 25^\circ\text{C}$, unless otherwise specified)
		min. typ. max.
V_{DSS}	$V_{GS} = 0\text{ V}$, $I_D = 1\text{ mA}$ V_{DSS} temperature coefficient	500 0.102 V/%K
$V_{GS(th)}$	$V_{DS} = V_{GS}$, $I_D = 4\text{ mA}$ $V_{GS(th)}$ temperature coefficient	2 -0.206 V/%K
I_{GSS}	$V_{GS} = \pm 20\text{ V}_{DC}$, $V_{DS} = 0$	± 100 nA
I_{DSS}	$V_{DS} = 0.8 \cdot V_{DSS}$, $T_J = 25^\circ\text{C}$ $V_{GS} = 0\text{ V}$, $T_J = 125^\circ\text{C}$	200 1 μA mA
$R_{DS(on)}$	$V_{GS} = 10\text{ V}$, $I_D = 15\text{ A}$ Pulse test, $t \leq 300\text{ }\mu\text{s}$, duty cycle $d \leq 2\%$	32N50 0.15 Ω 30N50 0.16 Ω

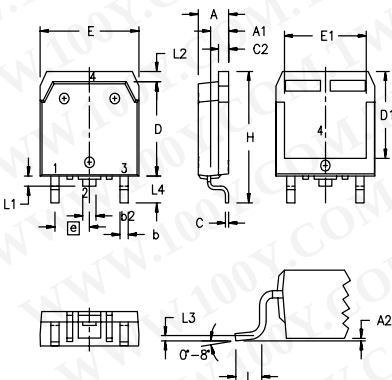
Symbol	Test Conditions	Characteristic Values ($T_J = 25^\circ\text{C}$, unless otherwise specified)		
		min.	typ.	max.
g_{fs}	$V_{DS} = 10\text{ V}; I_D = 0.5 I_{D25}$ pulse test	18	28	S
C_{iss}	$V_{GS} = 0\text{ V}, V_{DS} = 25\text{ V}, f = 1\text{ MHz}$	5200		5700 pF
C_{oss}		640		750 pF
C_{rss}		240		310 pF
$t_{d(on)}$	$V_{GS} = 10\text{ V}, V_{DS} = 0.5 V_{DSS}, I_D = 0.5 I_{D25}$ $R_G = 2\ \Omega$ (External)		35	45 ns
t_r			42	50 ns
$t_{d(off)}$			110	140 ns
t_f			26	35 ns
$Q_{g(on)}$	$V_{GS} = 10\text{ V}, V_{DS} = 0.5 V_{DSS}, I_D = 0.5 I_{D25}$		227	300 nC
Q_{gs}			29	40 nC
Q_{gd}			110	145 nC
R_{thJC}	(TO-247 Case Style)			0.35 K/W
R_{thCK}			0.25	K/W

TO-247 AD (IXFH) Outline



Dim.	Millimeter		Inches	
	Min.	Max.	Min.	Max.
A	19.81	20.32	0.780	0.800
B	20.80	21.46	0.819	0.845
C	15.75	16.26	0.610	0.640
D	3.55	3.65	0.140	0.144
E	4.32	5.49	0.170	0.216
F	5.4	6.2	0.212	0.244
G	1.65	2.13	0.065	0.084
H	-	4.5	-	0.177
J	1.0	1.4	0.040	0.055
K	10.8	11.0	0.426	0.433
L	4.7	5.3	0.185	0.209
M	0.4	0.8	0.016	0.031
N	1.5	2.49	0.087	0.102

Symbol	Test Conditions	Characteristic Values ($T_J = 25^\circ\text{C}$, unless otherwise specified)		
		min.	typ.	max.
I_S	$V_{GS} = 0\text{ V}$	30N50 32N50		30 32 A
I_{SM}	Repetitive; pulse width limited by T_{JM}	30N50 32N50		120 128 A
V_{SD}	$I_F = I_S, V_{GS} = 0\text{ V},$ Pulse test, $t \leq 300\ \mu\text{s}$, duty cycle $d \leq 2\%$			1.5 V
t_{rr}	$I_F = I_S$ $-di/dt = 100\text{ A}/\mu\text{s},$ $V_R = 100\text{ V}$	$T_J = 25^\circ\text{C}$		250 ns
Q_{RM}		$T_J = 125^\circ\text{C}$		400 ns
I_{RM}		$T_J = 25^\circ\text{C}$	0.85	μC
		$T_J = 25^\circ\text{C}$	8	A

TO-268AA (D³ PAK)

Dim.	Millimeter		Inches	
	Min.	Max.	Min.	Max.
A	4.9	5.1	.193	.201
A ₁	2.7	2.9	.106	.114
A ₂	.02	.25	.001	.010
b	1.15	1.45	.045	.057
b ₂	1.9	2.1	.75	.83
C	.4	.65	.016	.026
D	13.80	14.00	.543	.551
E	15.85	16.05	.624	.632
E ₁	13.3	13.6	.524	.535
e	5.45 BSC		.215 BSC	
H	18.70	19.10	.736	.752
L	2.40	2.70	.094	.106
L ₁	1.20	1.40	.047	.055
L ₂	1.00	1.15	.039	.045
L ₃	0.25 BSC		.010 BSC	
L ₄	3.80	4.10	.150	.161

Min. Recommended Footprint

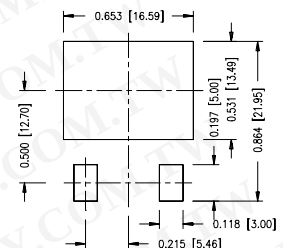


Figure 1. Output Characteristics at 25°C

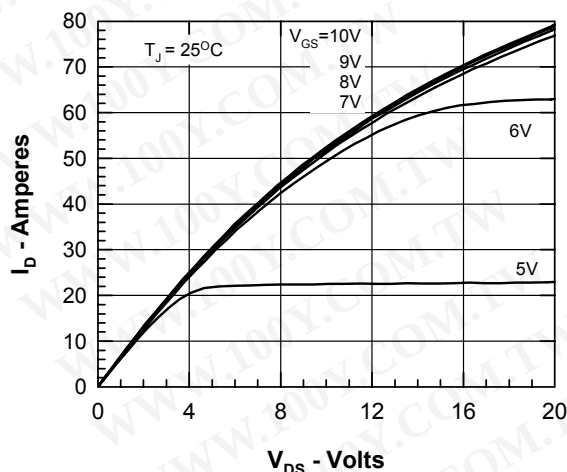


Figure 2. Output Characteristics at 125°C

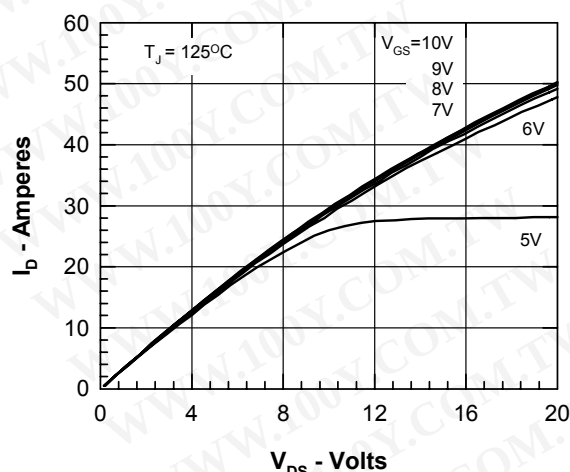


Figure 3. $R_{DS(on)}$ normalized to 15A/25°C vs. I_D

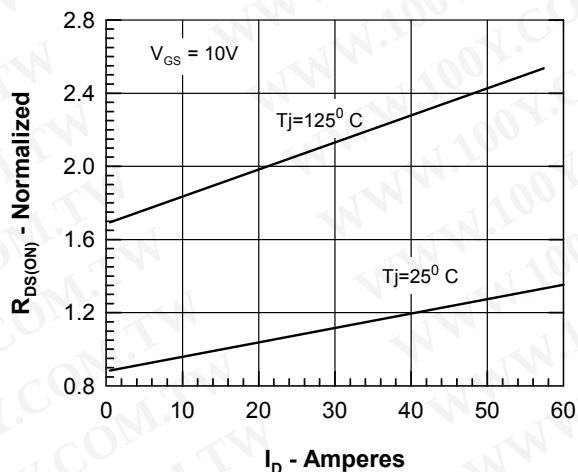


Figure 4. $R_{DS(on)}$ normalized to 15A/25°C vs. T_J

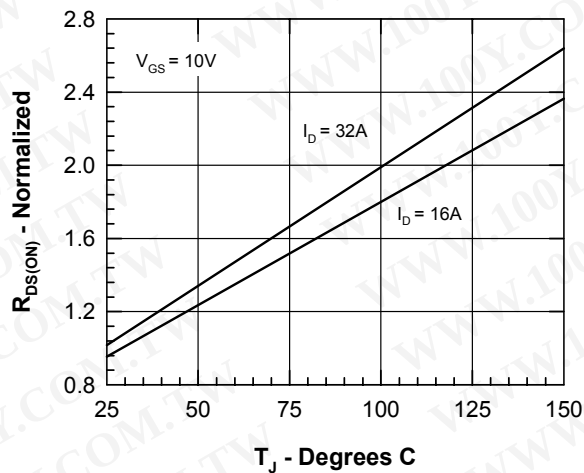


Figure 5. Drain Current vs. Case Temperature

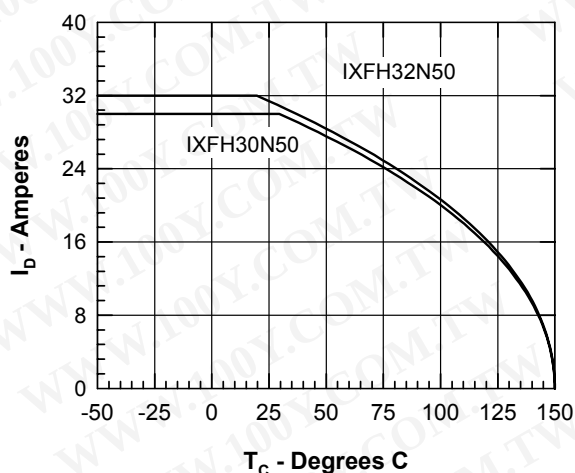


Figure 6. Admittance Curves

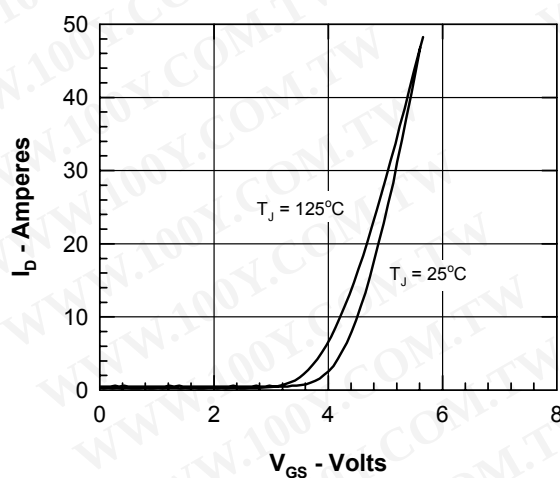


Figure 7. Gate Charge

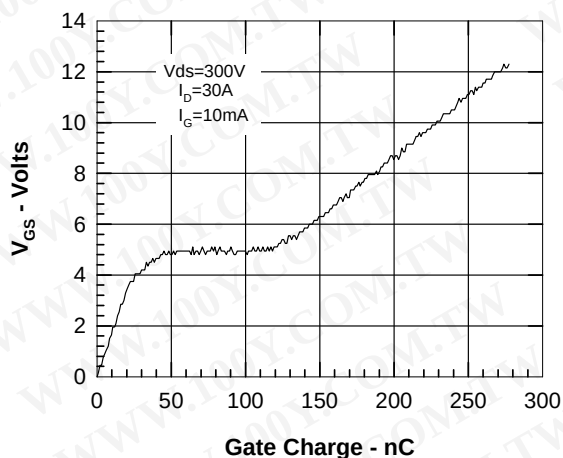


Figure 8. Capacitance Curves

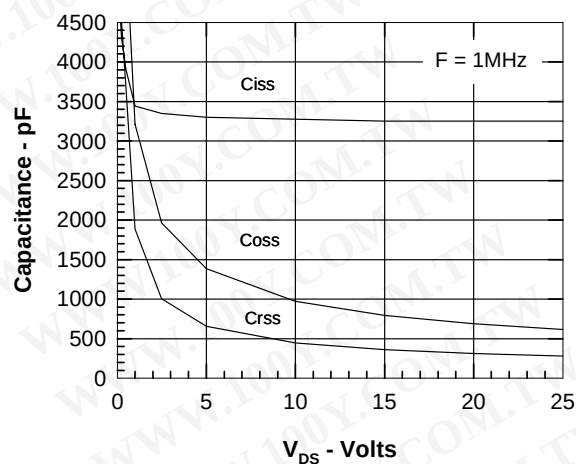
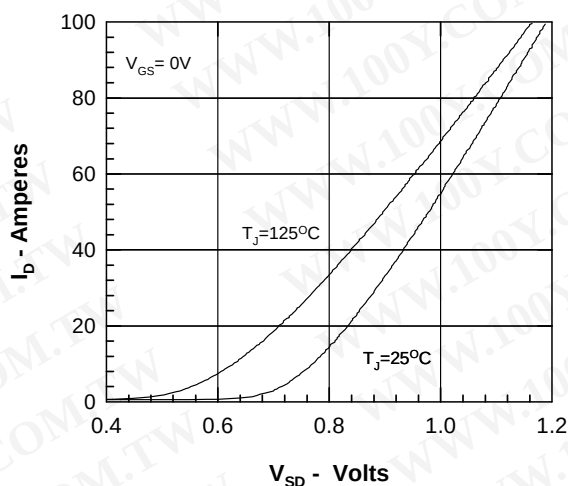


Figure 9. Forward Voltage Drop of the Intrinsic Diode



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Figure 10. Transient Thermal Resistance

